

## Review Form 1.6

Journal Name:	<a href="#">Journal of Engineering Research and Reports</a>
Manuscript Number:	Ms_JERR_88623
Title of the Manuscript:	Machine Capability Enhancement to Address Lacking Epoxy Coverage During Die Attach Process of QFN Packages
Type of the Article	Original Research Article

### General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<https://www.journaljerr.com/index.php/JERR/editorial-policy> )

### PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
<b>Compulsory</b> REVISION comments	Accept after revision	
<b>Minor</b> REVISION comments	Check grammar for the whole article Follow journal guidelines  Add following references  Chong D, Lim LY. Feasibility study on replacing conventional epoxy dispensing with wafer back coating epoxy for QFN packages for discrete product. In2008 33rd IEEE/CPMT International Electronics Manufacturing Technology Conference (IEMT) 2008 Nov 4 (pp. 1-6). IEEE.  Hoe YY, Jie YG, Rao VS, Rhee MW. Modeling and characterization of the thermal performance of advanced packaging materials in the flip-chip BGA and QFN packages. In2012 IEEE 14th Electronics Packaging Technology Conference (EPTC) 2012 Dec 5 (pp. 525-532). IEEE.	
<b>Optional/General</b> comments		

### PART 2:

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	(If yes, Kindly please write down the ethical issues here in details)	

### Reviewer Details:

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